

# Material Composition Specification

## SOD-80 Case



Device average mass . . . . . 28 mg  
 Fluctuation margin . . . . . +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.11%	0.03	Si	7440-21-3	0.11%	0.03	1,071
leadframe	Fe alloy w/ silver plating	56.32%	15.77	Cu	7440-50-8	8.93%	2.5	89,286
				Fe	7439-89-6	23.93%	6.7	239,286
				Ni	7440-02-0	21.07%	5.9	210,714
				Ag	7440-22-4	2.39%	0.67	23,929
encapsulation	glass	40.0%	11.2	SiO <sub>2</sub>	7631-86-9	16.96%	4.75	169,643
				Pb	7439-92-1	23.04%	6.45	230,357
plating*	tin/lead process	3.57%	1.0	Sn	7440-31-5	2.86%	0.8	28,571
				Pb	7439-92-1	0.71%	0.2	7,143
	matte tin	3.57%	1.0	Sn	7440-31-5	3.57%	1.0	35,714

\*For Lead Free plating, add suffix "PB FREE" to part number.  
 For Tin/Lead plating, add suffix "TIN/LEAD" to part number.  
 No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

**Disclaimer**

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R5 (16-July 2018)